

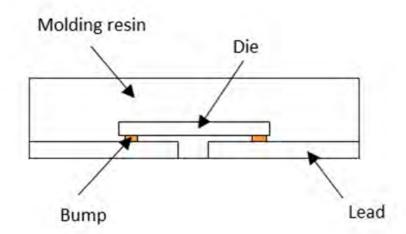
## Package Information: VQFN11X3535A

## 1. Package Information

Package Name VQFN11X3535A

Type QFN
Pin Count 11
Package Weight [g] 0.02
Lead Finish Pure Tin
MSL Level1

## 2. Package Structure



## 3. Packing Specification

3.1 Packing form, Quantity, PIN1 Orientation

Packing Form Tape&Reel
Packing Quantity [pcs] 2500
PIN 1 Orientation E2

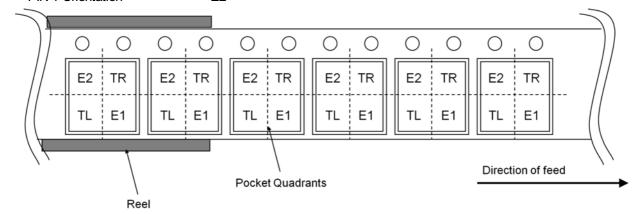


Fig.1 Quadrant Assignments for PIN 1 Orientation in Tape

E2 : PIN1 is placed to the top left corner. TR : PIN1 is placed to the top right corner.

TL: PIN1 is placed to the lower left. E1: PIN1 is placed to the lower right.

Fig. 1 PIN 1 Orientation in Tape

#### 3.2 Use material

Item	Material
Embossed carrier tape	PS
Cover tape	PET+PE
Reel	PS
Unit box	Cardboard
Shipping box	Cardboard

#### 3.3 Leader specification

No component pockets are 100 mm or more.

#### 3.4 Trailer specification

No component pockets are 40 mm or more. Tape is free from reel.

#### 3.5 Peelback strength

Cover tape peelback strength is 0.2 N to 0.7 N.

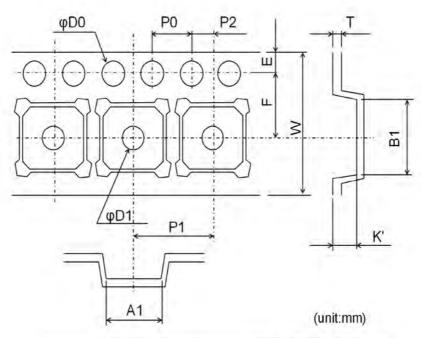
Peelback Peelback speed 300±10mm/min

Fig. 2 Test method

#### 3.6 Missing Ics

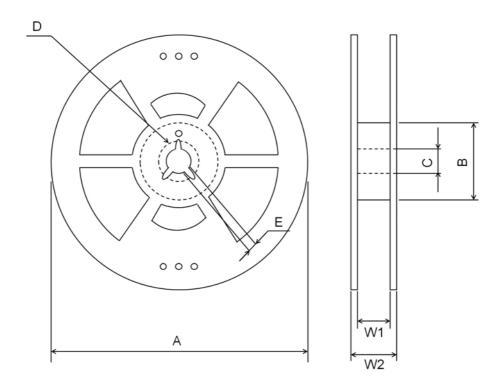
- (1) No consecutive dropouts.
- (2) A maximun 0.1 % of specified number of products in each packing may be missing.

# 3.7 Tape and Reel Specification 3.7.1 Tape Dimension



	Tape Dimension	Tape Tolerance
A1	3.7	±0.1
31	3.7	±0.1
00	φ1.5	+0.1/-0
1	φ1.5	±0.1
	1.75	±0.1
. 1	5.5	±0.05
6/	0.85	±0.1
0	4.0	±0.1
1	8.0	±0.1
2	2.0	±0.1
	0.25	±0.05
Ν	12.0	±0.2

## 3.7.2 Reel Dimension

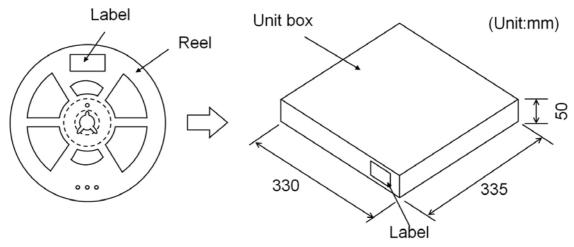


(unit:mm)

	Reel Dimension	Reel Tolerance
Α	330	±2.0
В	80	+1.0
С	13.0	±0.2
D	21	±0.8
Ε	2.0	±0.5
W1	13.5	±1.0
W2	17.5	±1.0

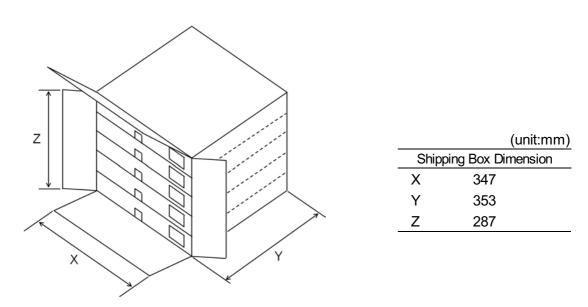
## 3.8 Packing Method

3 reel(s) or less per unit box



## 3.9 Packing Style

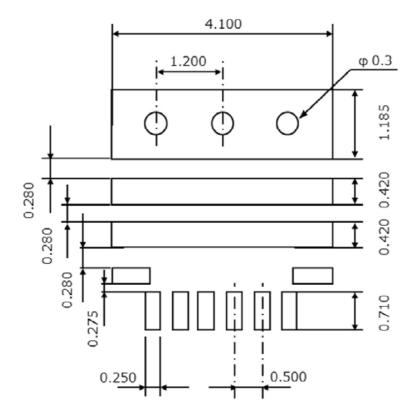
4 unit boxes or less per shipping box



## 3.10 Label Specification



## 4. Footprint dimensions



(unit:mm)

In actual design, please optimize in accordance with the situation of your board design and soldering condition.

## 5. Marking Specification



## 6. Storage conditions

## 6.1 Storage environment

Recommended storage conditions

	Min.	Max.	Unit
Temperature	5	30	°C
Humidity	-	85	% RH

## 6.2 Storage period (Start to count since delivery date)

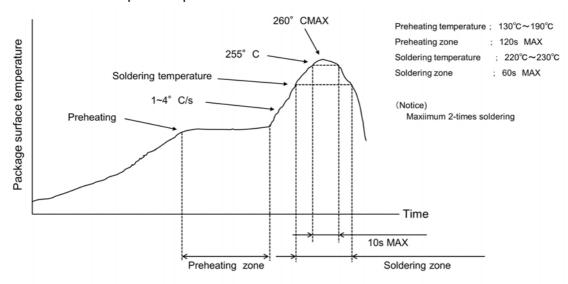
	Min.	Max.	Unit
Storage period	-	1	year

## 6.3 Drying process

Dryprocess is not required before solder mounting.

## 7. Soldering conditions

## 7.1 Recommended temperature profile for reflow

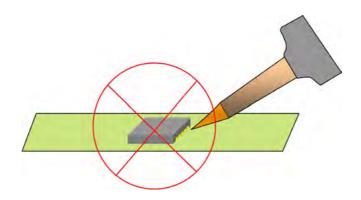


#### 7.2 For wave soldering

The wave soldering method is not supported.

#### 7.3 For solder iron

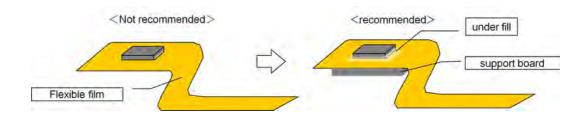
Rework by soldering iron is not allowed or it may cause mold crack and terminal open.



## 7.4 Caution for solder mounting

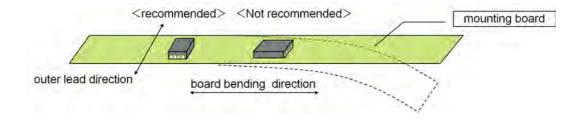
#### 7.4.1 For mounting on flexible film

Mounting on flexible film, film bend may occur lack of lead from package, usage of support board and under fill is recommended.



#### 7.4.2 For Mounting long and narrow board

Mounting on long and narrow board, bending stress may occur a luck of lead from package, bending board direction and outer lead direction is recommended as drawing (vertically layout) and under fill usage is recommended.



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